

CM1244

4-Channel ESD Array in CSP

Features

- Four Channels of ESD Protection
- ± 15 kV ESD Protection on Each Channel (IEC 61000-4-2 Level 4, Contact Discharge)
- ± 30 kV ESD Protection on Each Channel (HBM)
- Chip Scale Package Features Extremely Low Lead Inductance for Optimum ESD Protection
- 5-bump, 0.760 mm x 1.053 mm Footprint, 0.4 mm Pitch, Chip Scale Package (CSP)
- *OptiGuard™* Coating for Improved Reliability at Assembly
- These Devices are Pb-Free and are RoHS Compliant

Applications

- ESD Protection for Sensitive Electronic Equipment
- I/O Port and Keypad and Button Circuitry Protection for Portable Devices
- Can be Used for EMI Filtering when Combined with External Series Resistance
- Wireless Handsets
- Handheld PCs/PDAs
- MP3 Players
- Digital Camcorders
- Notebooks
- Desktop PCs



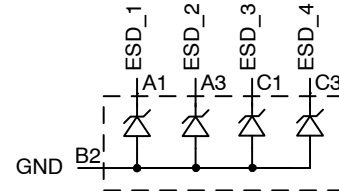
ON Semiconductor®

<http://onsemi.com>

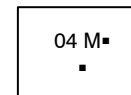


WLCSP5
CP SUFFIX
CASE 567AX

BLOCK DIAGRAM



MARKING DIAGRAM



04 = Specific Device Code
M = Date Code
▪ = Pb-Free Package
(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping†
CM1244-04CP	CSP-5 (Pb-Free)	3500/Tape & Reel

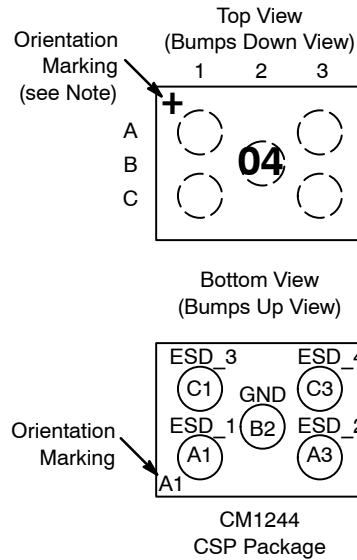
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

CM1244

Table 1. PIN DESCRIPTIONS

5-bump CSP Package		
Pin	Name	Description
A1	ESD_1	ESD Channel 1
A3	ESD_2	ESD Channel 2
B2	GND	Device Ground
C1	ESD_3	ESD Channel 3
C3	ESD_4	ESD Channel 4

PACKAGE / PINOUT DIAGRAMS



Note: The "+" orientation marking indicates that the package is lead-free.

SPECIFICATIONS

Table 2. ABSOLUTE MAXIMUM RATINGS

Parameter	Rating	Units
Storage Temperature Range	-65 to +150	°C
DC Package Power Rating	200	mW

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

Table 3. STANDARD OPERATING CONDITIONS

Parameter	Rating	Units
Operating Temperature Range	-40 to +85	°C

Table 4. ELECTRICAL OPERATING CHARACTERISTICS (Note 1)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
V _{DIODE}	Diode Reverse Breakdown Voltage	I _{DIODE} = 10 μA	5.5			V
I _{LEAK}	Diode Leakage Current	T _A = 25°C; V _{IN} = 3.3 V			100	nA
V _{SIG}	Signal Voltage Positive Clamp Negative Clamp	I _{DIODE} = 10 mA	5.6 -1.5	6.8 -0.8	9.0 -0.4	V
V _{ESD}	In-system ESD Withstand Voltage a) Human Body Model, MIL-STD-883, Method 3015 b) Contact Discharge per IEC 61000-4-2	(Note 2)	±30 ±15			kV
V _{CL}	Clamping Voltage during ESD Discharge MIL-STD-883 (Method 3015), 8 kV Positive Transients Negative Transients	(Note 2)		+15 -8		V
C _{DIODE}	Diode Capacitance	At 2.5 VDC Reverse Bias, 1 MHz, 30 mVAC	22	27	32	pF

1. T_A = -40°C to +85°C unless otherwise specified.
2. ESD applied to input and output pins with respect to GND, one at a time.

APPLICATION INFORMATION

Refer to Application Note “The Chip Scale Package,” for a detailed description of Chip Scale Packages offered by ON Semiconductor.

PERFORMANCE INFORMATION

Diode Characteristics (nominal conditions unless specified otherwise)

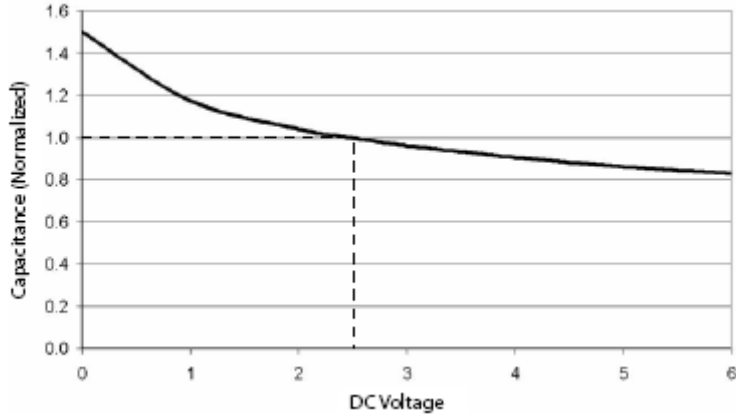


Figure 1. Typical Diode Capacitance vs. Input Voltage (normalized to 2.5 VDC)

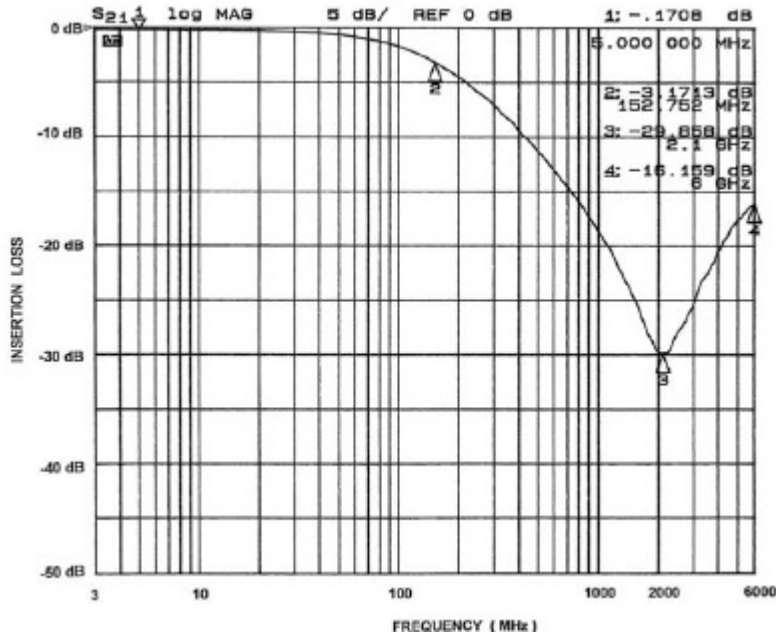


Figure 2. Frequency Response (single channel vs. GND, in 50 Ω system)

MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

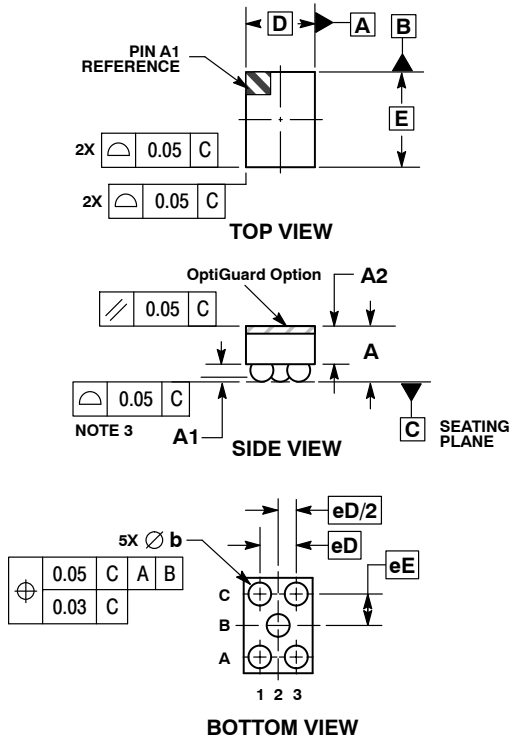
ON Semiconductor®



SCALE 4:1

WLCSP5, 0.76x1.05
CASE 567AX-01
ISSUE O

DATE 26 JUL 2010

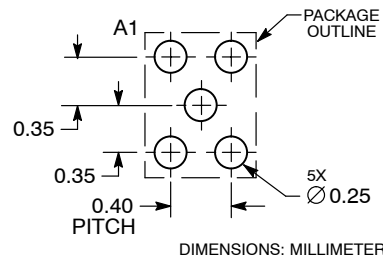


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.54	0.69
A1	0.17	0.24
A2	0.42	REF
b	0.24	0.29
D	0.76	BSC
E	1.05	BSC
eD	0.400	BSC
eE	0.347	BSC

**RECOMMENDED
SOLDERING FOOTPRINT***



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

DOCUMENT NUMBER:	98AON49807E	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	WLCSP5, 0.76X1.05	PAGE 1 OF 1

ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.

ON Semiconductor and  are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that ON Semiconductor was negligent regarding the design or manufacture of the part. ON Semiconductor is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Email Requests to: orderlit@onsemi.com

ON Semiconductor Website: www.onsemi.com

TECHNICAL SUPPORT

North American Technical Support:
Voice Mail: 1 800-282-9855 Toll Free USA/Canada
Phone: 011 421 33 790 2910

Europe, Middle East and Africa Technical Support:

Phone: 00421 33 790 2910

For additional information, please contact your local Sales Representative